

## Press News

March 18, 2015

### **DEK and SIPLACE at NEPCON Korea 2015: Solutions for High Accuracy and High Flexibility requirements**

At the Nepcon Korea 2015 trade show (April 1-3), ASM process specialists will demonstrate several of the latest DEK and SIPLACE technologies, with particular emphasis on products engineered for the most advanced applications requiring high accuracy and high flexibility. One of the highlights will be the new SIPLACE X4i S micron placement solution, which combines a placement speed of up to 120,000 cph (components per hour) with the outstanding placement accuracy of 25 µm at 3σ, thus providing a powerful solution for demanding applications like embedded PCBs, high-density placement or wafer-level fan-out. The award-winning DEK Horizon 01iX showcased at the booth will be configured with DEK HawkEye 1700 print verification, ProDEK dynamic closed-loop control and other productivity-enhancing tools. This printer configuration provides the speed, process control, quality and accuracy automotive electronics specialists demand. Collectively, the DEK and SIPLACE teams deliver one of the most comprehensive resources for SMT process knowledge and optimisation in the industry.

#### **SIPLACE Placement Solutions**

Addressing the demands of the automotive electronics and semiconductor sectors, where process adaptability and superb accuracy are non-negotiable, ASM's SIPLACE X4i S micron platform is configurable with two types of placement heads for the ultimate in flexibility and precision. The versatility of the SIPLACE MultiStar placement head allows manufacturers to switch between various modes: collect-and-place, pick-and-place, and mixed. In addition, dual conveyors manage different board sizes, JTF-M (SIPLACE JEDEC Tray Feeder) accommodates tray-supplied components, and the dip module seamlessly handles dipping requirements. All of these features combine to offer unmatched adaptability for dynamic manufacturing environments. The SIPLACE X4i S micron's flexibility is also matched by its precision. Leveraging the 20-nozzle SIPLACE SpeedStar placement head with its accuracy of 25 µm at 3 sigma, the minimum distance between components is reduced to as little as 75 µm. And the component spectrum ranges from the smallest of devices, the 03015, to

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packages as large as 6 mm x 6 mm, all which can be placed at speeds of 120,000 components per hour. This impressive platform, along with the full portfolio of advanced SIPLACE software for planning, NPI and production optimisation, will be demonstrated throughout the three-day NEPCON Korea event.

### **DEK Printing Solutions**

Like SIPLACE, the DEK printing technologies displayed at NEPCON Korea uniquely meet the accuracy and throughput needs of automotive electronics manufacturers in the region. The DEK Horizon 01iX showcased at the booth will be configured with advanced tools such as DEK HawkEye 1700 print verification, ProDEK dynamic closed-loop control, DEK Single Sweep Cyclone ultra-fast understencil cleaning, DEK Verification and Traceability software, and the DEK High Throughput Conveyor. Together, these technologies provide the speed, process control, quality and accuracy automotive electronics specialists demand. With the market's best alignment capability of 2 Cpk at  $\pm 12.5 \mu\text{m}$  6-sigma, a 7-second cycle time and fast understencil cleaning with DEK Single Sweep Cyclone, the DEK Horizon 01iX allows automotive manufacturers to realise exceptional throughput and high yields. The award-winning DEK Horizon 01iX's performance is further enhanced with DEK process support products such as DEK VectorGuard High Tension stencils, DEK Pro and ProXF understencil cleaning chemistries and DEK UFP ECO understencil fabric rolls. All of them will be shown at ASM booths D117 and E117.

### **Together #1 for SMT Process Expertise**

Collectively, the DEK and SIPLACE teams deliver the most comprehensive resources for SMT process knowledge and optimisation. This expertise is available at NEPCON Korea for all attendees at the ASM booth, where DEK and SIPLACE technology specialists will share solutions for current and future manufacturing challenges. In fact, ASM has already proven its capability for 0.3 mm CSP and 03015 printing and placement and will make this information available. Everyone is invited to utilise this invaluable resource to improve their manufacturing efficiency and prepare for future technologies.

To schedule an appointment, contact our specialists at: [dekmarketing@asmpt.com](mailto:dekmarketing@asmpt.com) or [siplace.kr@asmpt.com](mailto:siplace.kr@asmpt.com).



The DEK Horizon 01iX is the ideal platform for automotive electronics production, providing exceptional throughput, accuracy and control.



The SIPLACE X4i S micron unites flexibility and accuracy with its SIPLACE MultiStar and SIPLACE SpeedStar placement heads, along with advanced software capability.

#### **About The SMT Solutions Segment of ASMPT**

With the integration of DEK into ASM Pacific Technology (ASMPT) in July 2014, ASM Assembly Systems consists of the Printing Solutions Division (DEK) and the Placement Solutions Division (SIPLACE). ASM Assembly Systems develops and distributes best-in-class DEK printers, stencils and printing accessories for the SMT, semiconductor and solar markets, as well as best-in-class SIPLACE SMT placement solutions. Both Divisions leverage the power of ASM's development capabilities to deliver significant competitive advantages to customers. By sharing its knowledge and expertise, the SMT Solutions Segment of ASM provides electronics manufacturing companies worldwide with more effective process integration technology and optimised workflows.

For more information about DEK Printing Solutions, visit [www.dek.com](http://www.dek.com)

For more information about SIPLACE Placement Solutions, visit [www.siplace.com](http://www.siplace.com)

**ASM Pacific Technology Limited**

ASM Pacific Technology (ASMPT) has been listed on the Hong Kong Stock Exchange since 1989. The ASMPT Group develops systems and solutions for semiconductor production and packaging as well as surface mount technology applications. The company has plants in Hong Kong, China, Singapore, Malaysia and Germany.

ASMPT is currently one of the constituent stocks on the Hang Seng HK MidCap Index under the Hang Seng Composite Index, the Hang Seng Information Technology Industry Index, the Hang Seng Hong Kong 35 index and the Hang Seng Global Composite Index.

For more information about ASMPT, visit [www.asmpacific.com](http://www.asmpacific.com)

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